

# **Maximum Ratings** (@ $T_A = +25$ °C, unless otherwise specified.)

Single phase, half wave, 60Hz, resistive or inductive load.

For capacitive load, derate current by 20%.

Characteristic	Symbol	US1JDFQ	US1MDFQ	Unit
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage	V <sub>RRM</sub> V <sub>RWM</sub> V <sub>R</sub>	600	1000	V
RMS Reverse Voltage	V <sub>R(RMS)</sub>	420	700	V
Average Rectified Output Current $@T_T = +25^{\circ}C$	lo	1.	0	Α
Non-Repetitive Peak Forward Surge Current 8.3ms Single Half Sine-Wave Superimposed on Rated Load	I <sub>FSM</sub>	30	)	Α

### **Thermal Characteristics**

Characteristic	Symbol	Value	Unit
Typical Thermal Resistance, Junction to Terminal (Note 8)	$R_{\theta JT}$	44	°C/W
Typical Thermal Resistance, Junction to Ambient (Note 8)	$R_{\theta JA}$	80	°C/W
Operating and Storage Temperature Range	T <sub>J,</sub> T <sub>STG</sub>	-55 to +150	°C

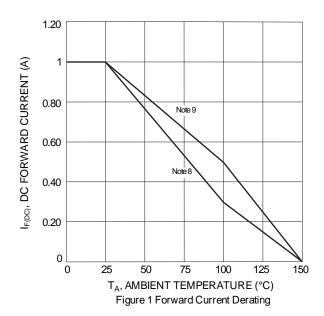
# **Electrical Characteristics** (@T<sub>A</sub> = +25°C, unless otherwise specified.)

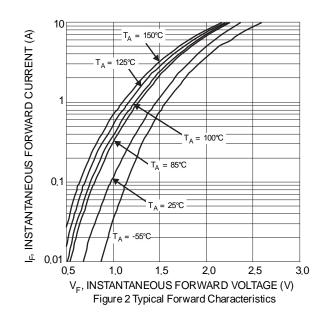
Characteristic		Symbol	US1JDFQ	US1MDFQ	Unit
Minimum Reverse Breakdown Voltage (Note 6)	$@I_R = 5\mu A$	$V_{(BR)R}$	600	1000	V
Maximum Forward Voltage Drop	@I <sub>F</sub> = 1.0A	$V_{F}$	1	.7	V
Peak Reverse Current	$@T_A = +25^{\circ}C$	1-	5	5.0	uА
at Rated DC Blocking Voltage (Note 6)	$@T_A = +100^{\circ}C$	IR	1	00	μΑ
Maximum Reverse Recovery Time (Note 7)		$t_{RR}$	7	75	ns
Typical Total Capacitance (Note 10)		Ст		10	pF

Notes:

- 6. Short duration pulse test used to minimize self-heating effect.
- 7. Measured with  $I_F$  = 0.5A,  $I_R$  = 1.0A,  $I_{RR}$  = 0.25A. See Figure 7.
- 8. Device mounted on FR-4 substrate, 1" \* 1", 2oz, single-sided, PC boards with 0.1" \* 0.15" copper pads.

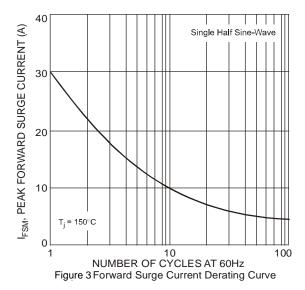
  9. Device mounted on FR-4 substrate, 0.4" \* 0.5", 2oz, single-sided, PC boards with 0.2" \* 0.25" copper pads.
- 10. Measured at 1.0MHz and applied reverse voltage of 4.0V DC.

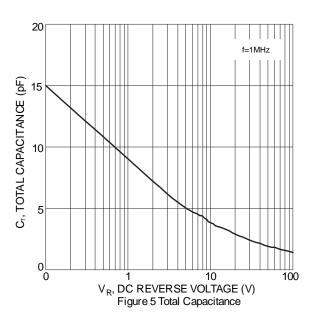


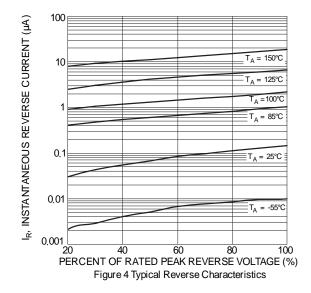


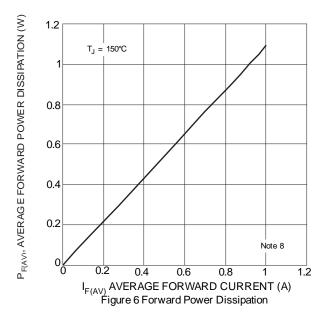














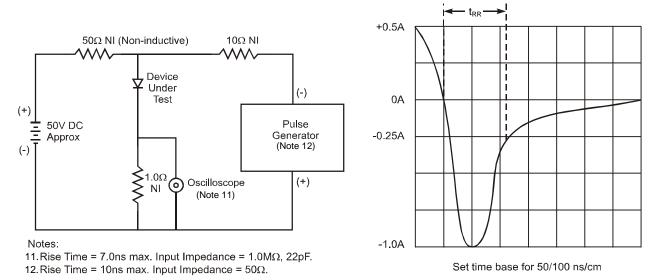
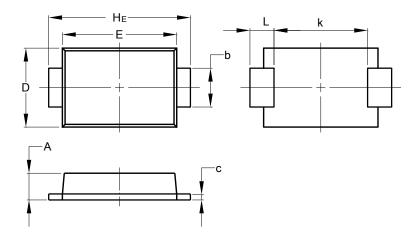


Figure 7 Reverse Recovery Time Characteristic and Test Circuit

### **Package Outline Dimensions**

Please see http://www.diodes.com/package-outlines.html for the latest version.

#### **D-FLAT**

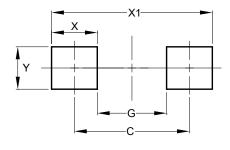


D-FLAT		
Dim	Min	Max
Α	0.90	1.10
b	1.25	1.65
C	0.10	0.40
D	2.25	2.95
Е	3.95	4.60
k	2.80	-
HE	5.00	5.60
L	0.50	1.30
All Dimensions in mm		

### **Suggested Pad Layout**

Please see http://www.diodes.com/package-outlines.html for the latest version.

### **D-FLAT**



Dimensions	Value (in mm)
С	4.65
G	2.80
X	1.85
X1	6.50
Υ	1.70



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